

ABSTRACT OF THE DISCLOSURE

The present invention relates to a substrate processing apparatus and a substrate processing method which are useful for

5 removing a metal, organic materials such as a resist material and etching residues, particles, and the like adhering to a surface of a substrate, such as a semiconductor wafer. The substrate processing apparatus according to the present invention includes: a substrate holder for holding a substrate;

10 a plurality of anodes and cathodes disposed opposite the substrate when held by the substrate holder and arranged alternately along at least one direction; a processing liquid supply section for supplying a processing liquid between the substrate held by the substrate holder and the plurality of anodes

15 and cathodes; and a power source for applying a voltage between the anodes and the cathodes.